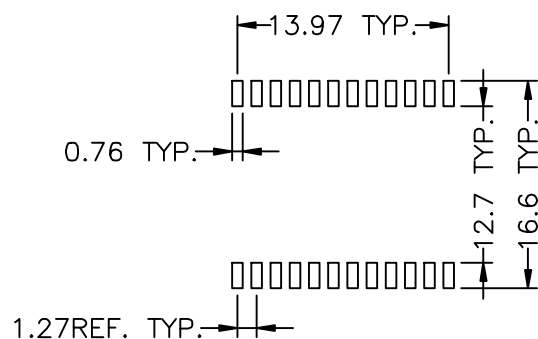
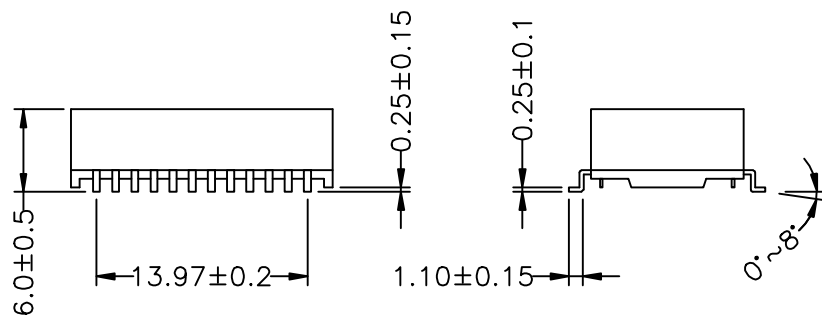
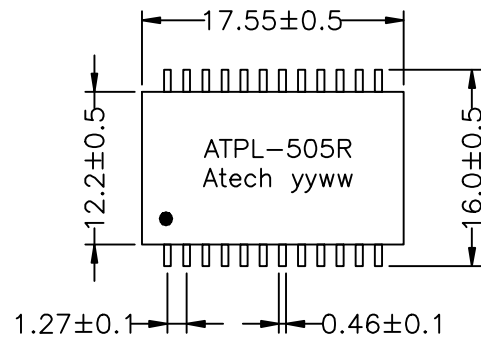
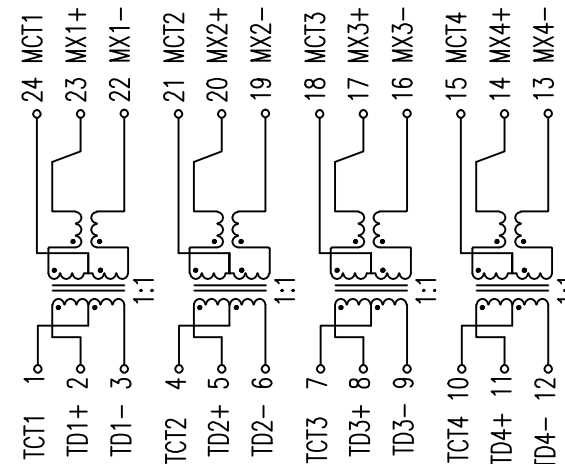




SUGGESTED PAD LAYOUT



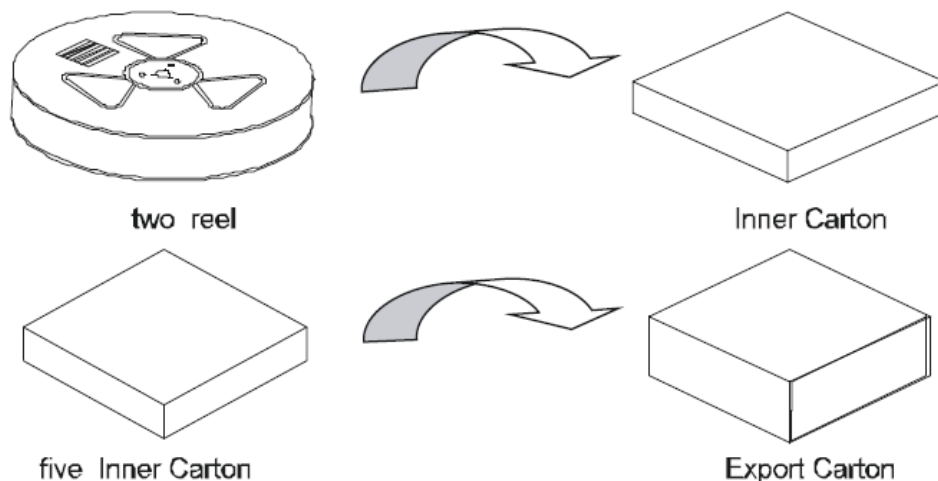
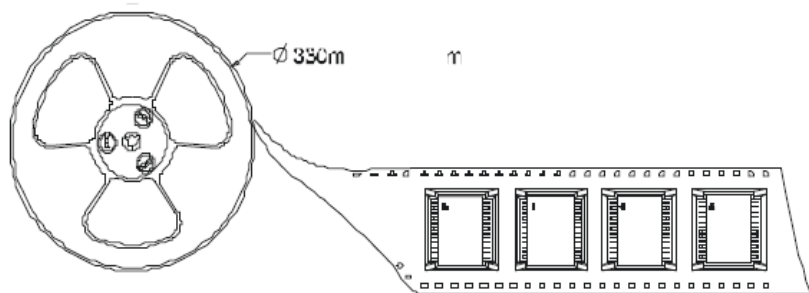
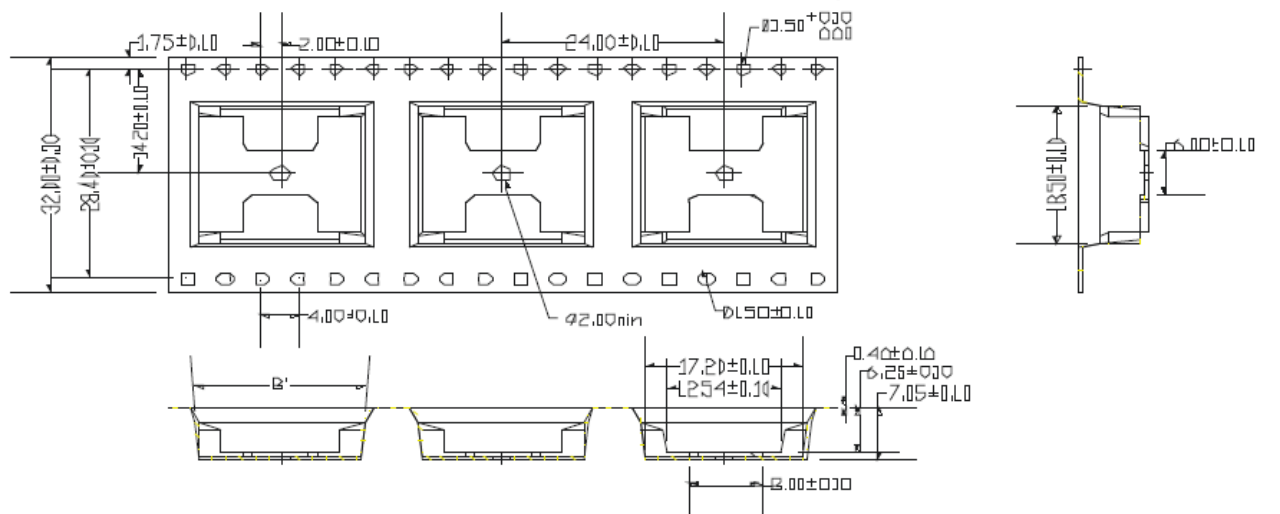
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS@25°C

1. OCL : (@100kHz, 0.1V) : 350uH MIN.
2. LEAKAGE INDUCTANCE : (@100kHz, 0.1V) : 0.5uH MAX.
3. DCR : 1.0Ω MAX.
4. TURNS RATIO : 1CT : 1CT ±5%
5. INSERTION LOSS : (@1-150MHz) : -1.5dB MAX.
6. RETURN LOSS : PHY SIDE TO LINE SIDE (ON LOAD 100Ω)
 - (@1-30MHz) : -20dB MIN.
 - (@30-60MHz) : -16dB MIN.
 - (@60-80MHz) : -14dB MIN.
 - (@80-100MHz) : -12dB MIN.
 - (@100-125MHz) : -10dB MIN.
 - (@125-150MHz) : -8dB MIN.
7. CROSS TALK : (@1-150MHz) : -30dB MIN.
8. COMMON MODE REJECTION : (@1-150MHz) : -30dB MIN.
9. ISOLATION HIPOT : (@1500VAC, 1mA, 60S)
10. OPERATING TEMPERATURE : 0°C TO +70°C
11. STORAGE TEMPERATURE : -25°C TO +125°C

								TITLE 2.5G BASE-T TRANSFORMER	
								DWG. NO. ATPL-505R	
	RELEASE	12/21/2016	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 OF 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 12/21/16	P/N:		DRAW SHIRLEY
REVISIONS									

3. Package :



Package Quantity:

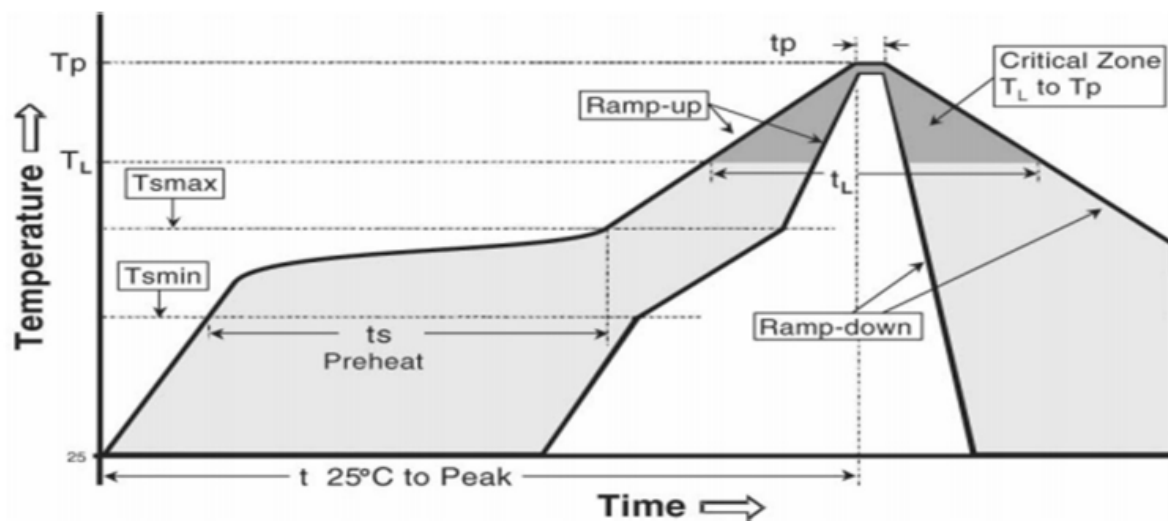
One Reel=350Pcs

One Inner Carton=350*2=700Pcs

One Export Carton=700*5=3500Pcs

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmmax)	150°C	200°C
Time (Tsmmin to Tsmmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max